Qualcomm

Qualcomm Technologies, Inc.

Qualcomm® Robotics RB3 Platform
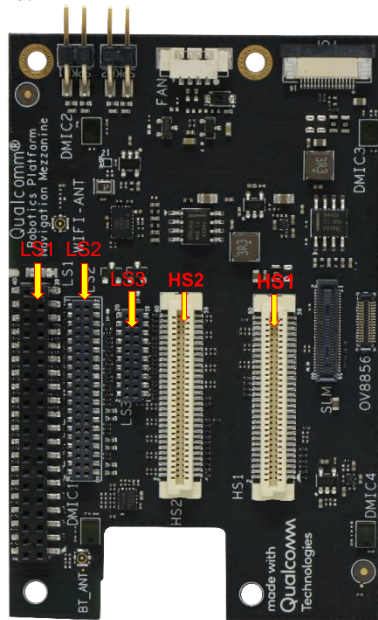
Navigation Mezzanine Specifications

Rev. A

February 15, 2019

Qualcomm Technologies, Inc.
5775 Morehouse Drive
San Diego, CA 92121
U.S.A.

Revision history

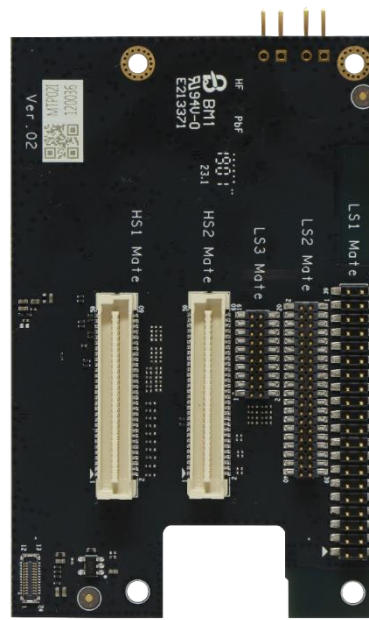| Revision	Date	Description
A	February 2019	Initial release

Navigation Mezzanine development board

The Navigation Mezzanine development board can be used to connect four different cameras directly by MIPI CSI interface: Main Camera, Tracking Camera, ToF Camera, and SLM Camera.It supports three cameras concurrency.It is ideal for developers to enable rapid development of embedded vision applications.

| Top view | Back view |

Technical specifications

Component	Description
Expansion interfaces	Expansion connectors: ▪ HS1:1 x 60 pin high-speed connector (4L-MIPI DSI, USB 2.0 x2, I2C x 2, SDIO) ▪ HS2:1 x 60 pin high-speed connector (SSC SPI, PCIe 3.0, USB 3.0 x 1, GPIO < 9) ▪ LS1:1 x 96boards 40 pin low-speed connector (UART x 2, I2S, I2C x 2, GPIO x 8, DC power) ▪ LS2:1 x 96boards 40 pin low-speed connector (headset, stereo speaker, DMIC I/F x 1, CAN, I2S, GPIO x 7, PWM x1, ADC x 2) ▪ LS3:1 x 96boards 20 pin Low-Speed connector (SSC I2C, sensor interrupt x 1)
Other Interfaces	▪ Main Camera Connector & Tracking Camera Connector & ToF Camera Connector & SLM Camera Connector ▪ 1 x Fan Connector ▪ 2 x Speaker Connectors ▪ 4 x DMICs on-board
Sensor	▪ 1 x 6-Axis Sensor, 1 x Pressure Sensor, 1 x Compass
Antenna	▪ Dedicated 2.4GHz Bluetooth printed antenna on board
Size	▪ 85 mm x 54 mm meeting 96Boards Consumer Edition Standard form dimensions specifications